Listing of Claims:

1. (Previously Presented) An In-plane switching (IPS) mode LCD device comprising:

first and second substrates opposite each other, each substrate having an active region and a dummy region;

gate and data lines substantially perpendicular to each other;

a pixel electrode and a common electrode in the active region of the first substrate;

a black matrix layer in the dummy region of the second substrate;

a UV-hardening sealant at a circumference of the black matrix layer between the first and second substrates, wherein the UV-hardening sealant bonds the first and second substrates together;

a metal pattern between the UV-hardening sealant and the first substrate; and

a liquid crystal layer between the first and second substrates bonded by the UV-hardening sealant,

wherein the metal pattern completely overlaps the UV-hardening sealant and is formed at four edges of the first substrate.

2. (Previously Presented) The IPS mode LCD device of claim 1, wherein the metal pattern is of the same material as the gate line.

3. (Original) The IPS mode LCD device of claim 1, wherein the UV-hardening sealant includes one of epoxy acrylate resin, urethane acrylate resin and polyester acrylate.

4. (Original) The IPS mode LCD of claim 1, further including column spacers for maintaining a cell gap between the first and second substrates, and an overcoat layer.

5. (Withdrawn) An IPS mode LCD device comprising:

first and second substrates opposite to each other, each substrate having an active region and a dummy region;

a black matrix layer in the dummy region of the second substrate;

a UV-hardening sealant at a circumference of the black matrix layer between the first and second substrates, wherein the UV-hardening sealant is used for bonding the first and second substrates to each other;

a liquid crystal layer between the first and second substrates bonded by the UV-hardening sealant.

6. (Withdrawn) The IPS mode LCD device of claim 5, wherein the first substrate has an IPS mode thin film transistor array including gate and data lines substantially perpendicular to each other, a pixel electrode and a common electrode in the active region thereof.

7. (Withdrawn) The IPS mode LCD device of claim 5, wherein the UV-hardening sealant includes one of epoxy acrylate resin, urethane acrylate resin and polyester acrylate.

8. (Withdrawn) The IPS mode LCD devide of claim 5, further including column spacers for maintaining a cell gap between the first and second substrates, and an overcoat layer.

9. (Previously Presented) A method for manufacturing an IPS mode LCD device comprising:

forming gate lines crossing data lines on a first substrate;

forming a pixel electrode and a common electrode on the first substrate;

forming a metal pattern in a dummy region of the first substrate having active and dummy regions;

forming a black matrix layer in a dummy region of a second substrate having active and dummy regions;

depositing a UV-hardening sealant at a circumference of the black matrix layer on the second substrate;

bonding the first and second substrates to each other after placing the UV-hardening sealant to the first substrate; and

irradiating a UV ray to harden the UV-hardening sealant;

wherein the metal pattern completely overlaps the UV-hardening sealant and is formed at four edges of the first substrate.

10. (Original) The method of claim 9, wherein the UV-hardening sealant includes one of epoxy acrylate resin, urethane acrylate resin and polyester acrylate.

11. (Original) The method of claim 9, wherein the metal pattern is formed of the same material as a gate line.

12. (Original) The method of claim 9, further comprising dispensing liquid crystal on the active region of the first substrate before bonding the first and second substrates together.

13. (Original) The method of claim 9, wherein the UV-hardening sealant is completely hardened with the UV ray reflected from the metal pattern.

14. (Withdrawn) A method for manufacturing an IPS mode LCD device comprising:

forming a black matrix layer in a dummy region of a second substrate having active and dummy regions;

depositing a UV-hardening sealant at a circumference of the black matrix layer on the second substrate;

bonding the first and second substrates to each other after facing the UV-hardening sealant to the first substrate; and

irradiating a UV ray to harden the UV-hardening sealant.

15. (Withdrawn) The method of claim 14, further comprising dispensing a liquid crystal on the active region of the first substrate before bonding the first and second substrate together.

16. (Withdrawn) The method of claim 14, wherein the UV-hardening sealant includes one of epoxy acrylate resin, urethane acrylate resin and polyester acrylate.